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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	XCore
Core Size	32-Bit 6-Core
Speed	500MIPS
Connectivity	Configurable
Peripherals	-
Number of I/O	28
Program Memory Size	64KB (16K x 32)
Program Memory Type	SRAM
EEPROM Size	-
RAM Size	-
Voltage - Supply (Vcc/Vdd)	0.95V ~ 3.6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP Exposed Pad
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/xmos/xs1-l6a-64-tq48-i5

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- ▶ **Channels and channel ends** Tasks running on logical cores communicate using channels formed between two channel ends. Data can be passed synchronously or asynchronously between the channel ends assigned to the communicating tasks. Section [5.5](#)
- ▶ **xCONNECT Switch and Links** Between tiles, channel communications are implemented over a high performance network of xCONNECT Links and routed through a hardware xCONNECT Switch. Section [5.6](#)
- ▶ **Ports** The I/O pins are connected to the processing cores by Hardware Response ports. The port logic can drive its pins high and low, or it can sample the value on its pins optionally waiting for a particular condition. Section [5.3](#)
- ▶ **Clock blocks** xCORE devices include a set of programmable clock blocks that can be used to govern the rate at which ports execute. Section [5.4](#)
- ▶ **Memory** Each xCORE Tile integrates a bank of SRAM for instructions and data, and a block of one-time programmable (OTP) memory that can be configured for system wide security features. Section [8](#)
- ▶ **PLL** The PLL is used to create a high-speed processor clock given a low speed external oscillator. Section [6](#)
- ▶ **JTAG** The JTAG module can be used for loading programs, boundary scan testing, in-circuit source-level debugging and programming the OTP memory. Section [9](#)

1.1 Software

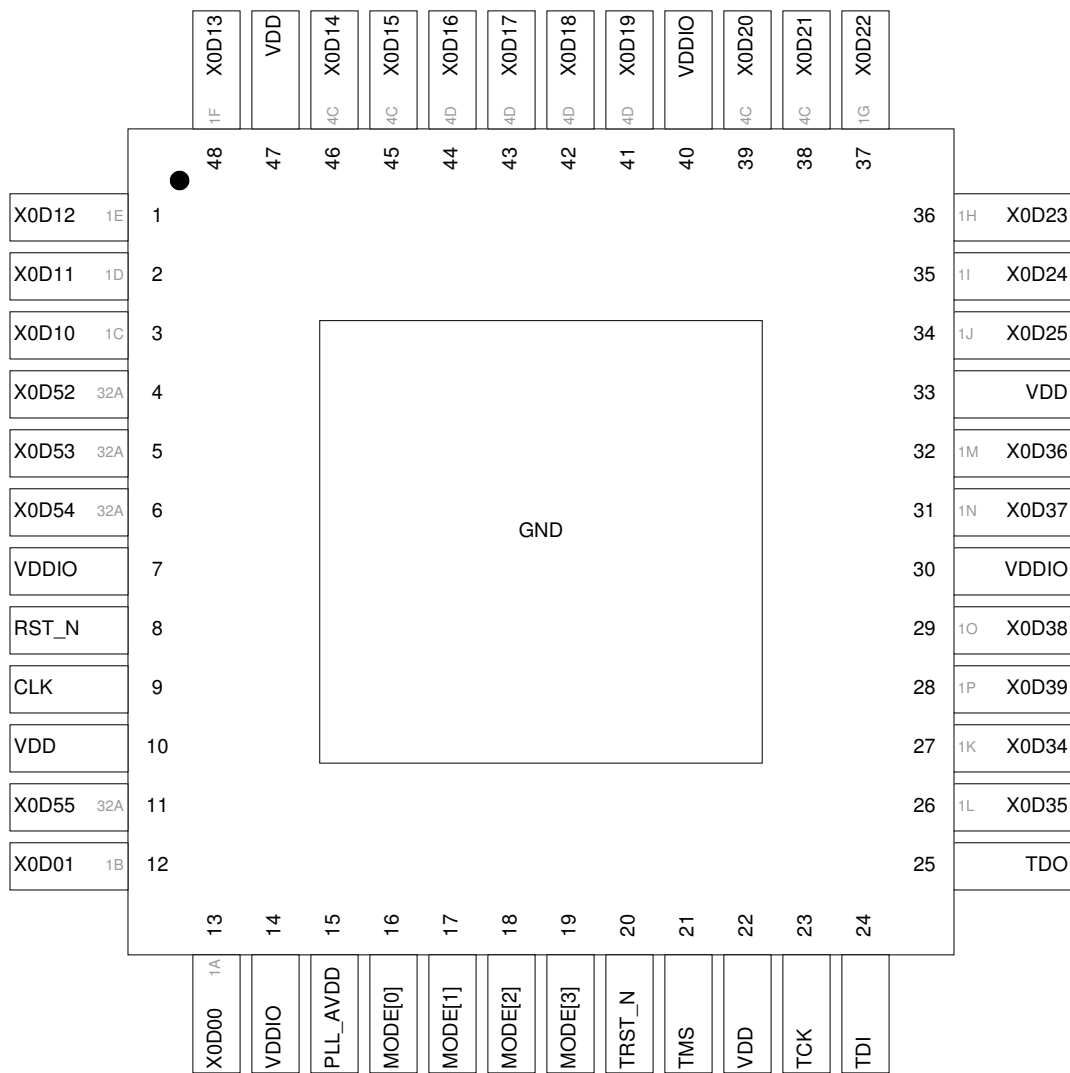
Devices are programmed using C, C++ or xC (C with multicore extensions). XMOS provides tested and proven software libraries, which allow you to quickly add interface and processor functionality such as USB, Ethernet, PWM, graphics driver, and audio EQ to your applications.

1.2 xTIMEcomposer Studio

The xTIMEcomposer Studio development environment provides all the tools you need to write and debug your programs, profile your application, and write images into flash memory or OTP memory on the device. Because xCORE devices operate deterministically, they can be simulated like hardware within xTIMEcomposer: uniquely in the embedded world, xTIMEcomposer Studio therefore includes a static timing analyzer, cycle-accurate simulator, and high-speed in-circuit instrumentation.

xTIMEcomposer can be driven from either a graphical development environment, or the command line. The tools are supported on Windows, Linux and MacOS X and available at no cost from xmos.com/downloads. Information on using the tools is provided in the xTIMEcomposer User Guide, [X3766](#).

3 Pin Configuration



1. Allocate channel-end 0.
2. Input a word on channel-end 0. It will use this word as a channel to acknowledge the boot. Provide the null-channel-end 0x0000FF02 if no acknowledgment is required.
3. Input the boot image specified above, including the CRC.
4. Input an END control token.
5. Output an END control token to the channel-end received in step 2.
6. Free channel-end 0.
7. Jump to the loaded code.

7.3 Boot from OTP

If an xCORE tile is set to use secure boot (see Figure 7), the boot image is read from address 0 of the OTP memory in the tile's security module.

This feature can be used to implement a secure bootloader which loads an encrypted image from external flash, decrypts and CRC checks it with the processor, and discontinues the boot process if the decryption or CRC check fails. XMOS provides a default secure bootloader that can be written to the OTP along with secret decryption keys.

Each tile has its own individual OTP memory, and hence some tiles can be booted from OTP while others are booted from SPI or the channel interface. This enables systems to be partially programmed, dedicating one or more tiles to perform a particular function, leaving the other tiles user-programmable.

7.4 Security register

The security register enables security features on the xCORE tile. The features shown in Figure 10 provide a strong level of protection and are sufficient for providing strong IP security.

8 Memory

8.1 OTP

The xCORE Tile integrates 8 KB one-time programmable (OTP) memory along with a security register that configures system wide security features. The OTP holds data in four sectors each containing 512 rows of 32 bits which can be used to implement secure bootloaders and store encryption keys. Data for the security register is loaded from the OTP on power up. All additional data in OTP is copied from the OTP to SRAM and executed first on the processor.

The OTP memory is programmed using three special I/O ports: the OTP address port is a 16-bit port with resource ID 0x100200, the OTP data is written via a 32-bit

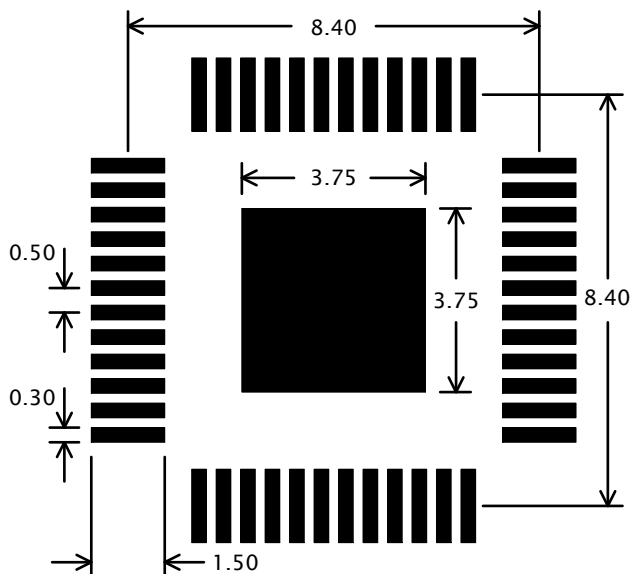


Figure 14:
Example land
pattern

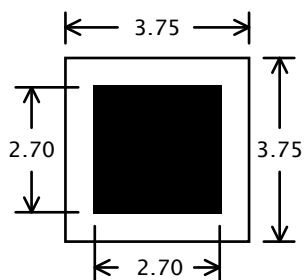


Figure 15:
Solder stencil
for centre
pad

11 DC and Switching Characteristics

11.1 Operating Conditions

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
VDD	Tile DC supply voltage	0.95	1.00	1.05	V	
VDDIO	I/O supply voltage	3.00	3.30	3.60	V	
PLL_AVDD	PLL analog supply	0.95	1.00	1.05	V	
CI	xCORE Tile I/O load capacitance			25	pF	
Ta	Ambient operating temperature	0		70	°C	
Ta	Ambient operating temperature	-40		85	°C	
Tj	Junction temperature			125	°C	
Tstg	Storage temperature	-65		150	°C	

Figure 16:
Operating conditions

11.2 DC Characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
V(IH)	Input high voltage	2.00		3.60	V	A
V(IL)	Input low voltage	-0.30		0.70	V	A
V(OH)	Output high voltage	2.00			V	B, C
V(OL)	Output low voltage			0.60	V	B, C
R(PU)	Pull-up resistance		35K		Ω	D
R(PD)	Pull-down resistance		35K		Ω	D

Figure 17:
DC characteristics

A All pins except power supply pins.

B Ports 1A, 1D, 1E, 1H, 1I, 1J, 1K and 1L are nominal 8 mA drivers, the remainder of the general-purpose I/Os are 4 mA.

C Measured with 4 mA drivers sourcing 4 mA, 8 mA drivers sourcing 8 mA.

D Used to guarantee logic state for an I/O when high impedance. The internal pull-ups/pull-downs should not be used to pull external circuitry.

11.3 ESD Stress Voltage

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
HBM	Human body model	-2.00		2.00	KV	
MM	Machine model	-200		200	V	

Figure 18:
ESD stress voltage

11.6 Clock

Figure 21:
Clock

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
f	Frequency	4.22	20	100	MHz	
SR	Slew rate	0.10			V/ns	
TJ(LT)	Long term jitter (pk-pk)			2	%	A
f(MAX)	Processor clock frequency (Speed Grade 4)			400	MHz	B
	Processor clock frequency (Speed Grade 5)			500	MHz	B

A Percentage of CLK period.

B Assumes typical tile and I/O voltages with nominal activity.

Further details can be found in the XS1-L Clock Frequency Control document, [X1433](#).

11.7 xCORE Tile I/O AC Characteristics

Figure 22:
I/O AC characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
T(XOVALID)	Input data valid window	8			ns	
T(XOINVALID)	Output data invalid window	9			ns	
T(XIFMAX)	Rate at which data can be sampled with respect to an external clock			60	MHz	

The input valid window parameter relates to the capability of the device to capture data input to the chip with respect to an external clock source. It is calculated as the sum of the input setup time and input hold time with respect to the external clock as measured at the pins. The output invalid window specifies the time for which an output is invalid with respect to the external clock. Note that these parameters are specified as a window rather than absolute numbers since the device provides functionality to delay the incoming clock with respect to the incoming data.

Information on interfacing to high-speed synchronous interfaces can be found in the XS1 Port I/O Timing document, [X5821](#).

11.8 xConnect Link Performance

Figure 23:
Link performance

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
B(2blinkP)	2b link bandwidth (packetized)			87	MBit/s	A, B
B(5blinkP)	5b link bandwidth (packetized)			217	MBit/s	A, B
B(2blinkS)	2b link bandwidth (streaming)			100	MBit/s	B
B(5blinkS)	5b link bandwidth (streaming)			250	MBit/s	B

A Assumes 32-byte packet in 3-byte header mode. Actual performance depends on size of the header and payload.

B 7.5 ns symbol time.

The asynchronous nature of links means that the relative phasing of CLK clocks is not important in a multi-clock system, providing each meets the required stability criteria.

11.9 JTAG Timing

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
f(TCK_D)	TCK frequency (debug)			18	MHz	
f(TCK_B)	TCK frequency (boundary scan)			10	MHz	
T(SETUP)	TDO to TCK setup time	5			ns	A
T(HOLD)	TDO to TCK hold time	5			ns	A
T(DELAY)	TCK to output delay			15	ns	B

Figure 24:
JTAG timing

A Timing applies to TMS and TDI inputs.

B Timing applies to TDO output from negative edge of TCK.

All JTAG operations are synchronous to TCK apart from the global asynchronous reset TRST_N.

The response to a write message comprises either control tokens 3 and 1 (for success), or control tokens 4 and 1 (for failure).

A read message comprises the following:

control-token 193	24-bit response channel-end identifier	16-bit register number	control-token 1
----------------------	---	---------------------------	--------------------

The response to the read message comprises either control token 3, 32-bit of data, and control-token 1 (for success), or control tokens 4 and 1 (for failure).

A.3 Accessing node configuration

Node configuration registers can be accessed through the interconnect using the functions `write_node_config_reg(device, ...)` and `read_node_config_reg(device, ↩ ...)`, where `device` is the name of the node. These functions implement the protocols described below.

Instead of using the functions above, a channel-end can be allocated to communicate with the node configuration registers. The destination of the channel-end should be set to `0xnnnnC30C` where `nnnn` is the node-identifier.

A write message comprises the following:

control-token 192	24-bit response channel-end identifier	16-bit register number	32-bit data	control-token 1
----------------------	---	---------------------------	----------------	--------------------

The response to a write message comprises either control tokens 3 and 1 (for success), or control tokens 4 and 1 (for failure).

A read message comprises the following:

control-token 193	24-bit response channel-end identifier	16-bit register number	control-token 1
----------------------	---	---------------------------	--------------------

The response to a read message comprises either control token 3, 32-bit of data, and control-token 1 (for success), or control tokens 4 and 1 (for failure).

0x03:
xCORE Tile
boot status

Bits	Perm	Init	Description
31:24	RO	-	Reserved
23:16	RO		xCORE tile number on the switch.
15:9	RO	-	Reserved
8	RO		Set to 1 if boot from OTP is enabled.
7:0	RO		The boot mode pins MODE0, MODE1, ..., specifying the boot frequency, boot source, etc.

B.5 Security configuration: 0x05

Copy of the security register as read from OTP.

0x05:
Security
configuration

Bits	Perm	Init	Description
31:0	RO		Value.

B.6 Ring Oscillator Control: 0x06

There are four free-running oscillators that clock four counters. The oscillators can be started and stopped using this register. The counters should only be read when the ring oscillator is stopped. The counter values can be read using four subsequent registers. The ring oscillators are asynchronous to the xCORE tile clock and can be used as a source of random bits.

0x06:
Ring
Oscillator
Control

Bits	Perm	Init	Description
31:2	RO	-	Reserved
1	RW	0	Set to 1 to enable the xCORE tile ring oscillators
0	RW	0	Set to 1 to enable the peripheral ring oscillators

B.7 Ring Oscillator Value: 0x07

This register contains the current count of the xCORE Tile Cell ring oscillator. This value is not reset on a system reset.

0x07:
Ring
Oscillator
Value

Bits	Perm	Init	Description
31:16	RO	-	Reserved
15:0	RO	-	Ring oscillator counter data.

0x15:
Debug
interrupt type

Bits	Perm	Init	Description
31:18	RO	-	Reserved
17:16	DRW		If the debug interrupt was caused by a hardware breakpoint or hardware watchpoint, this field contains the number of the breakpoint or watchpoint. If multiple breakpoints or watchpoints trigger at once, the lowest number is taken.
15:8	DRW		If the debug interrupt was caused by a logical core, this field contains the number of that core. Otherwise this field is 0.
7:3	RO	-	Reserved
2:0	DRW	0	Indicates the cause of the debug interrupt 1: Host initiated a debug interrupt through JTAG 2: Program executed a DCALL instruction 3: Instruction breakpoint 4: Data watch point 5: Resource watch point

B.17 Debug interrupt data: 0x16

On a data watchpoint, this register contains the effective address of the memory operation that triggered the debugger. On a resource watchpoint, it contains the resource identifier.

0x16:
Debug
interrupt data

Bits	Perm	Init	Description
31:0	DRW		Value.

B.18 Debug core control: 0x18

This register enables the debugger to temporarily disable logical cores. When returning from the debug interrupts, the cores set in this register will not execute. This enables single stepping to be implemented.

0x18:
Debug core
control

Bits	Perm	Init	Description
31:8	RO	-	Reserved
7:0	DRW		1-hot vector defining which logical cores are stopped when not in debug mode. Every bit which is set prevents the respective logical core from running.

0x04:
Control
PSwitch
permissions
to debug
registers

Bits	Perm	Init	Description
31:1	RO	-	Reserved
0	CRW		Set to 1 to restrict PSwitch access to all CRW marked registers to become read-only rather than read-write.

C.5 Cause debug interrupts: 0x05

This register can be used to raise a debug interrupt in this xCORE tile.

0x05:
Cause debug
interrupts

Bits	Perm	Init	Description
31:2	RO	-	Reserved
1	RO	0	Set to 1 when the processor is in debug mode.
0	CRW	0	Set to 1 to request a debug interrupt on the processor.

C.6 xCORE Tile clock divider: 0x06

This register contains the value used to divide the PLL clock to create the xCORE tile clock. The divider is enabled under control of the [tile control register](#)

0x06:
xCORE Tile
clock divider

Bits	Perm	Init	Description
31:8	RO	-	Reserved
7:0	RW		Value of the clock divider minus one.

C.7 Security configuration: 0x07

Copy of the security register as read from OTP.

0x07:
Security
configuration

Bits	Perm	Init	Description
31:0	RO		Value.

C.8 PLink status: 0x10 .. 0x13

Status of each of the four processor links; connecting the xCORE tile to the switch.

C.11 PC of logical core 1: 0x41

0x41:
PC of logical
core 1

Bits	Perm	Init	Description
31:0	RO		Value.

C.12 PC of logical core 2: 0x42

0x42:
PC of logical
core 2

Bits	Perm	Init	Description
31:0	RO		Value.

C.13 PC of logical core 3: 0x43

0x43:
PC of logical
core 3

Bits	Perm	Init	Description
31:0	RO		Value.

C.14 PC of logical core 4: 0x44

0x44:
PC of logical
core 4

Bits	Perm	Init	Description
31:0	RO		Value.

C.15 PC of logical core 5: 0x45

0x45:
PC of logical
core 5

Bits	Perm	Init	Description
31:0	RO		Value.

C.16 SR of logical core 0: 0x60

Value of the SR of logical core 0

0x0C:
Directions
0-7

Bits	Perm	Init	Description
31:28	RW	0	The direction for packets whose first mismatching bit is 7.
27:24	RW	0	The direction for packets whose first mismatching bit is 6.
23:20	RW	0	The direction for packets whose first mismatching bit is 5.
19:16	RW	0	The direction for packets whose first mismatching bit is 4.
15:12	RW	0	The direction for packets whose first mismatching bit is 3.
11:8	RW	0	The direction for packets whose first mismatching bit is 2.
7:4	RW	0	The direction for packets whose first mismatching bit is 1.
3:0	RW	0	The direction for packets whose first mismatching bit is 0.

D.9 Directions 8-15: 0x0D

This register contains eight directions, for packets with a mismatch in bits 15..8 of the node-identifier. The direction in which a packet will be routed is governed by the most significant mismatching bit.

0x0D:
Directions
8-15

Bits	Perm	Init	Description
31:28	RW	0	The direction for packets whose first mismatching bit is 15.
27:24	RW	0	The direction for packets whose first mismatching bit is 14.
23:20	RW	0	The direction for packets whose first mismatching bit is 13.
19:16	RW	0	The direction for packets whose first mismatching bit is 12.
15:12	RW	0	The direction for packets whose first mismatching bit is 11.
11:8	RW	0	The direction for packets whose first mismatching bit is 10.
7:4	RW	0	The direction for packets whose first mismatching bit is 9.
3:0	RW	0	The direction for packets whose first mismatching bit is 8.

D.10 DEBUG_N configuration: 0x10

Configures the behavior of the DEBUG_N pin.

0x10:
DEBUG_N
configuration

Bits	Perm	Init	Description
31:2	RO	-	Reserved
1	RW	0	Set to 1 to enable signals on DEBUG_N to generate DCALL on the core.
0	RW	0	When set to 1, the DEBUG_N wire will be pulled down when the node enters debug mode.

D.13 PLink status and network: 0x40 .. 0x43

These registers contain status information and the network number that each processor-link belongs to.

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:24	RO		If this link is currently routing data into the switch, this field specifies the type of link that the data is routed to: 0: plink 1: external link 2: internal control link
23:16	RO	0	If the link is routing data into the switch, this field specifies the destination link number to which all tokens are sent.
15:6	RO	-	Reserved
5:4	RW	0	Determines the network to which this link belongs, set for quality of service.
3	RO	-	Reserved
2	RO	0	Set to 1 if the current packet is junk and being thrown away. A packet is considered junk if, for example, it is not routable.
1	RO	0	Set to 1 if the switch is routing data into the link, and if a route exists from another link.
0	RO	0	Set to 1 if the link is routing data into the switch, and if a route is created to another link on the switch.

0x40 .. 0x43:
PLink status
and network

D.14 Link configuration and initialization: 0x80 .. 0x87

These registers contain configuration and debugging information specific to external links. The link speed and width can be set, the link can be initialized, and the link status can be monitored. The registers control links C, D, A, B, G, H, E, and F in that order.

0x80 .. 0x87:
Link
configuration
and
initialization

Bits	Perm	Init	Description
31	RW	0	Write '1' to this bit to enable the link, write '0' to disable it. This bit controls the muxing of ports with overlapping links.
30	RW	0	Set to 0 to operate in 2 wire mode or 1 to operate in 5 wire mode
29:28	RO	-	Reserved
27	RO	0	Set to 1 on error: an RX buffer overflow or illegal token encoding has been received. This bit clears on reading.
26	RO	0	1 if this end of the link has issued credit to allow the remote end to transmit.
25	RO	0	1 if this end of the link has credits to allow it to transmit.
24	WO	0	Set to 1 to initialize a half-duplex link. This clears this end of the link's credit and issues a HELLO token; the other side of the link will reply with credits. This bit is self-clearing.
23	WO	0	Set to 1 to reset the receiver. The next symbol that is detected will be assumed to be the first symbol in a token. This bit is self-clearing.
22	RO	-	Reserved
21:11	RW	0	The number of system clocks between two subsequent transitions within a token
10:0	RW	0	The number of system clocks between two subsequent transmit tokens.

D.15 Static link configuration: 0xA0 .. 0xA7

These registers are used for static (ie, non-routed) links. When a link is made static, all traffic is forwarded to the designated channel end and no routing is attempted. The registers control links C, D, A, B, G, H, E, and F in that order.

0xA0 .. 0xA7:
Static link
configuration

Bits	Perm	Init	Description
31	RW	0	Enable static forwarding.
30:5	RO	-	Reserved
4:0	RW	0	The destination channel end on this node that packets received in static mode are forwarded to.

G.3 Full xSYS header

For a full xSYS header you will need to connect the pins as discussed in Section G.2, and then connect a 2-wire xCONNECT Link to the xSYS header. The links can be found in the Signal description table (Section 4): they are labelled XLA, XLB, etc in the function column. The 2-wire link comprises two inputs and outputs, labelled ${}^1_{out}$, ${}^0_{out}$, ${}^0_{in}$, and ${}^1_{in}$. For example, if you choose to use XLB of tile 0 for xSCOPE I/O, you need to connect up ${}^1_{out}$, ${}^0_{out}$, ${}^0_{in}$, ${}^1_{in}$ as follows:

- ▶ ${}^1_{out}$ (X0D16) to pin 6 of the xSYS header with a 33R series resistor close to the device.
- ▶ ${}^0_{out}$ (X0D17) to pin 10 of the xSYS header with a 33R series resistor close to the device.
- ▶ ${}^0_{in}$ (X0D18) to pin 14 of the xSYS header.
- ▶ ${}^1_{in}$ (X0D19) to pin 18 of the xSYS header.

H Schematics Design Check List

- ✓ This section is a checklist for use by schematics designers using the XS1-L6A-64-TQ48. Each of the following sections contains items to check for each design.

H.1 Power supplies

- ☐ VDDIO supply is within specification before the VDD (core) supply is turned on. Specifically, the VDDIO supply is within specification before VDD (core) reaches 0.4V (Section 10).
- ☐ The VDD (core) supply ramps monotonically (rises constantly) from 0V to its final value (0.95V - 1.05V) within 10ms (Section 10).
- ☐ The VDD (core) supply is capable of supplying 300mA (Section 10).
- ☐ PLL_AVDD is filtered with a low pass filter, for example an RC filter, see Section 10

H.2 Power supply decoupling

- ☐ The design has multiple decoupling capacitors per supply, for example at least four 0402 or 0603 size surface mount capacitors of 100nF in value, per supply (Section 10).
- ☐ A bulk decoupling capacitor of at least 10uF is placed on each supply (Section 10).

H.3 Power on reset

- ☐ The RST_N and TRST_N pins are asserted (low) during or after power up. The device is not used until these resets have taken place. As the errata in the datasheets show, the internal pull-ups on these two pins can occasionally provide stronger than normal pull-up currents. For this reason, an RC type reset circuit is discouraged as behavior would be unpredictable. A voltage supervisor type reset device is recommended to guarantee a good reset. This also has the benefit of resetting the system should the relevant supply go out of specification.

H.4 Clock

- ☐ The CLK input pin is supplied with a clock with monotonic rising edges and low jitter.

- ☐ Pins MODE0 and MODE1 are set to the correct value for the chosen oscillator frequency. The MODE settings are shown in the Oscillator section, Section 6. If you have a choice between two values, choose the value with the highest multiplier ratio since that will boot faster.

H.5 USB ULPI Mode

This section can be skipped if you do not have an external USB PHY.

- ☐ If using ULPI, the ULPI signals are connected to specific ports as shown in Section E.
- ☐ If using ULPI, the ports that are used internally are not connected, see Section E. (Note that this limitation only applies when the ULPI is enabled, they can still be used before or after the ULPI is being used.)

H.6 Boot

- ☐ The device is connected to a SPI flash for booting, connected to X0D0, X0D01, X0D10, and X0D11 (Section 7). If not, you must boot the device through OTP or JTAG.
- ☐ The device that is connected to flash has both MODE2 and MODE3 connected to pin 3 on the xSYS Header (MSEL). If no debug adapter connection is supported (not recommended) MODE2 and MODE3 are to be left NC (Section 7).
- ☐ The SPI flash that you have chosen is supported by **xflash**, or you have created a specification file for it.

H.7 JTAG, XScope, and debugging

- ☐ You have decided as to whether you need an xSYS header or not (Section G)
- ☐ If you included an xSYS header, you connected pin 3 to any MODE2/MODE3 pin that would otherwise be NC (Section G).
- ☐ If you have not included an xSYS header, you have devised a method to program the SPI-flash or OTP (Section G).

H.8 GPIO

- ☐ You have not mapped both inputs and outputs to the same multi-bit port.

J Associated Design Documentation

Document Title	Information	Document Number
Estimating Power Consumption For XS1-L Devices	Power consumption	X4271
Programming XC on XMOS Devices	Timers, ports, clocks, cores and channels	X9577
xTIMEcomposer User Guide	Compilers, assembler and linker/mapper Timing analyzer, xScope, debugger Flash and OTP programming utilities	X3766

K Related Documentation

Document Title	Information	Document Number
The XMOS XS1 Architecture	ISA manual	X7879
XS1 Port I/O Timing	Port timings	X5821
xCONNECT Architecture	Link, switch and system information	X4249
XS1-L Link Performance and Design Guidelines	Link timings	X2999
XS1-L Clock Frequency Control	Advanced clock control	X1433
XS1-L Active Power Conservation	Low-power mode during idle	X7411